

1. Disassembly Procedures

S1 Turn off the monitor.

S2 To remove the stand:
Place the monitor on a soft cloth or cushion

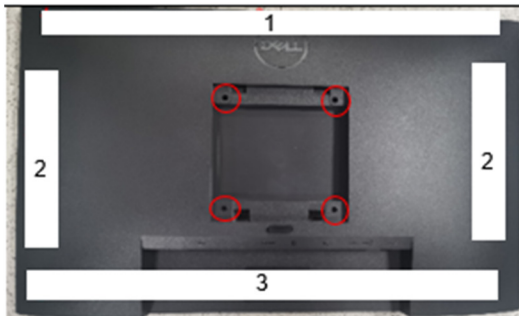
Press and hold the stand release button

Lift the stand up and away from the monitor



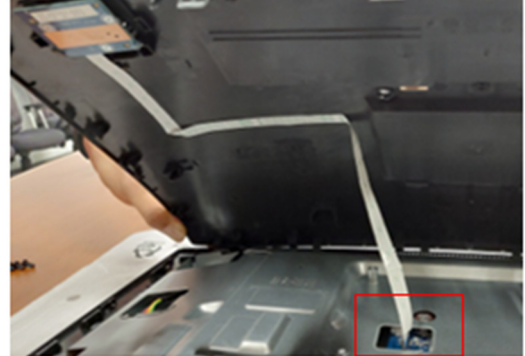
S3 Unlock 4 RC screws

Disassemble Rear Cover from Middle Frame according to the sequence shown in the picture



(Screw Torque: 9±1kgf)

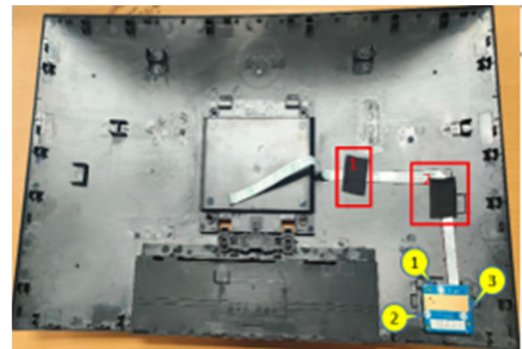
S4 Pull out CTRL BD FFC from I/F BD to take off Rear Cover



S5 Tear off the tapes from CTRL BD FFC on Rear Cover

Unlock 3 screws to disassemble CTRL BD from Rear Cover

Tear off CTRL BD FFC from Rear Cover and take off CTRL BD from Rear Cover

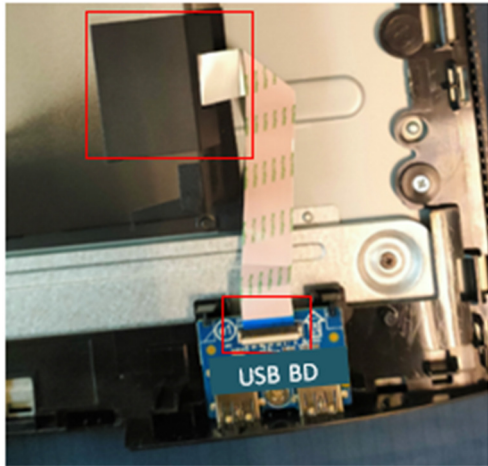


(Screw Torque: 2.0±0.5kgf)

- S6** Disassemble CTRL BD FFC from CTRL BD



- S7** Tear off malar from Main SHD
Disassemble USB FFC from USB BD and I/F BD



- S8** Unlock 1 screw on USB BD
Disassemble USB BD from Middle Frame

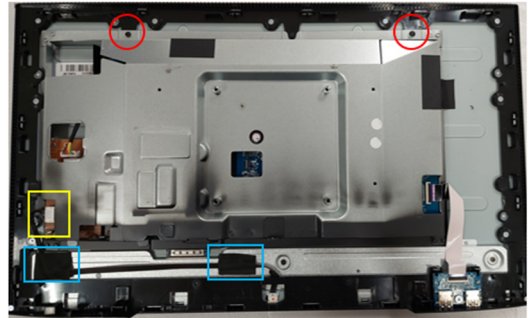


(Screw Torque-MF: 4.5±0.5kgf)

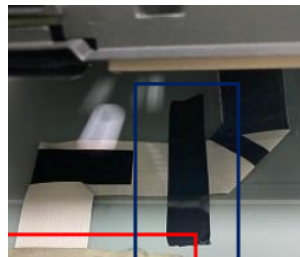
- S9** Tear off adhesive tapes on Backlight Wire

Pull out Backlight Wire from LED Driver BD

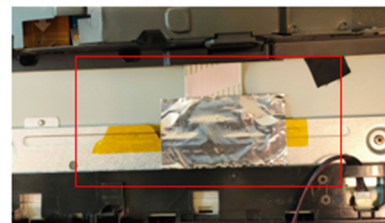
Disassemble Main SHD from Middle Frame



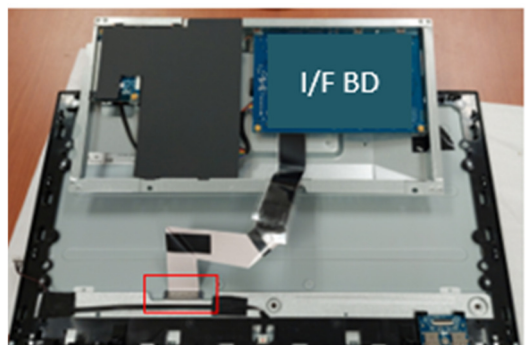
- S10** Tear off 1 tape from LVDS cable



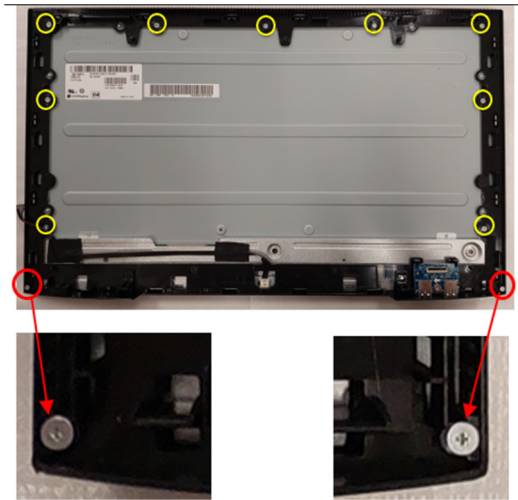
- S11** Tear off a 1 aluminum foil and a yellow tape from LVDS cable



- S12** Disassemble LVDS cable and take off Main SHD from panel



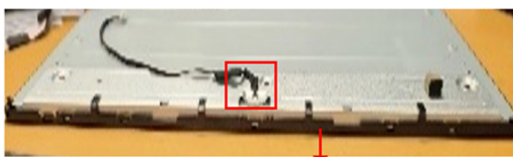
- S13** Unlock 9 screws on Middle Frame
Unlock 2 screws on Bezel Chin



(Screw Torque-MF: 4.5~5.0kgf)
(Screw Torque-BZL Chin: 2.0±0.5kgf)

- S14** Disassemble Middle Frame and Bezel Chin from Panel

Pull out Backlight Wire from panel

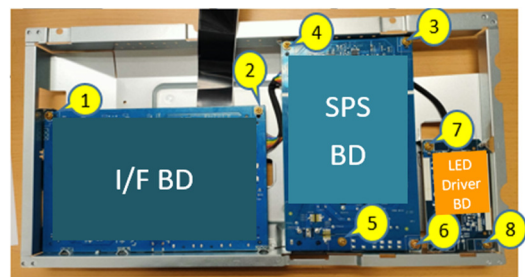


Bezel Chin

- S15** Disassemble Mylar from Main SHD



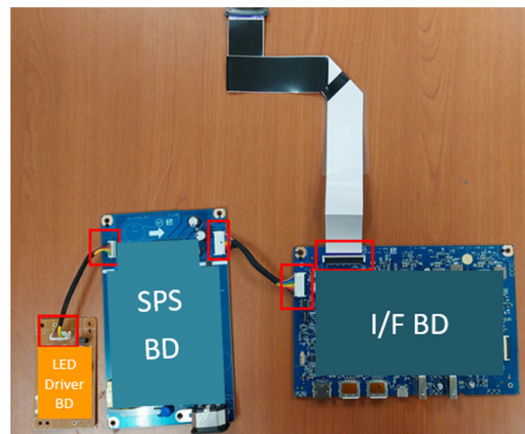
- S16** Unlock 8 PCB screws



(Screw Torque-MF: 8.5±1kgf)

- S17** Disassemble I/F BD, SPS BD, LED Driver BD from Main SHD

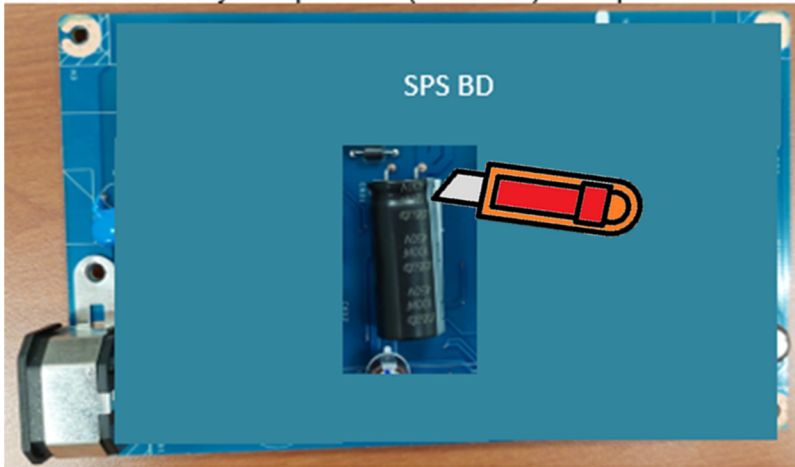
Pull out all cables from I/F BD, SPS BD and LED Driver BD



S18 Remove electrolyte capacitors (red mark) from printed circuit boards



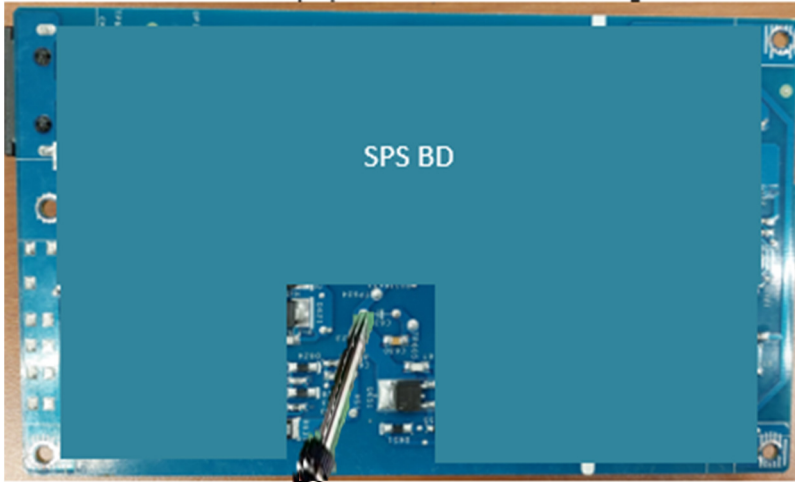
S18-1 Cut the glue between bulk cap. and PCB with a knife



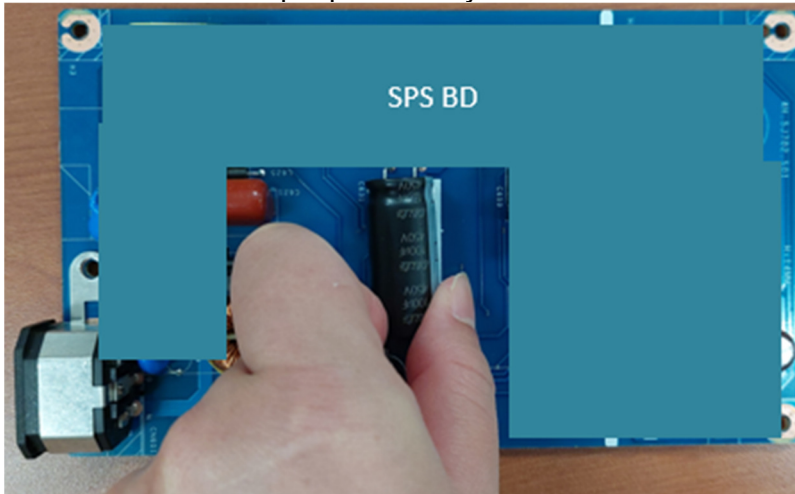
S18-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S18-3 Take out bulk cap. pin solder with soldering iron and absorber



S18-4 Lift the bulk cap. up and away from the PCB



2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater than 10 square cm)	Product has printed circuit boards (with a surface greater than 10 square cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and HC	No used
Gas discharge lamps	No used
LCD display > 100 cm ²	Product has an LCD greater than 100 cm ²
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height > 25mm, diameter > 25mm)	Product has electrolyte capacitors (height >25mm, diameter > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber